

1.5A, 200V - 600V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Lighting application
- Snubber
- Freewheeling application

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.064g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I _F	1.5	А
V _{RRM}	200 - 600	V
I _{FSM}	30	А
T _{J MAX}	150	°C
Package	DO-214AC (SMA)	
Configuration	Single die	





DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Marking code on the device		BYG20D	BYG20G	BYG20J	
Repetitive peak reverse voltage	V _{RRM}	200	400	600	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	V
Forward current	I _F	1.5		Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30		А	
Pulse energy in avalanche mode, non-repetitive (Inductive load switch off), L = 120mH	E _{RSM}	20		mJ	
Junction temperature	TJ	- 55 to +150		°C	
Storage temperature	T _{STG}	- 55 to +150		°C	



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THERMAL PERFORMANCE

PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	R _{eJL}	25	°C/W
Junction-to-ambient thermal resistance	R _{eja}	100	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)

		,			
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 1.0A, T_J = 25^{\circ}C$	V_{F}	-	1.3	V
	I _F = 1.5A, T _J = 25°C		-	1.4	V
Reverse current @ rated V _R ⁽²⁾	$T_J = 25^{\circ}C$	I _R	-	1	μA
	T _J = 100°C		-	10	μA
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	t _{rr}	-	75	ns

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
BYG20x	DO-214AC (SMA)	7,500 / Tape & Reel

Notes:

1. "x" defines voltage from 200V(BYG20D) to 600V(BYG20J)



10

REVERSE VOLTAGE (V)

Fig.4 Typical Forward Characteristics

100

CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

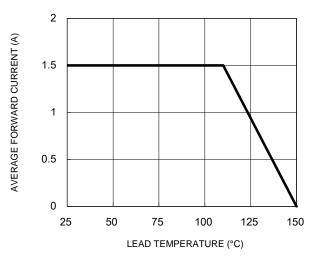


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

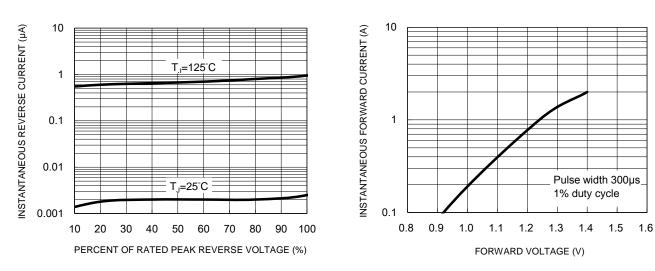


Fig.5 Maximum Non-Repetitive Forward Surge Current

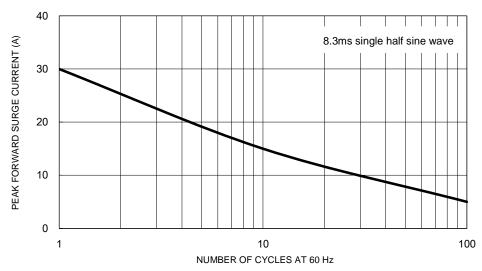


Fig.2 Typical Junction Capacitance

175

150

125

100

75 50

25

0

0.1

f=1.0MHz Vsig=50mVp-p

1

CAPACITANCE (pF)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

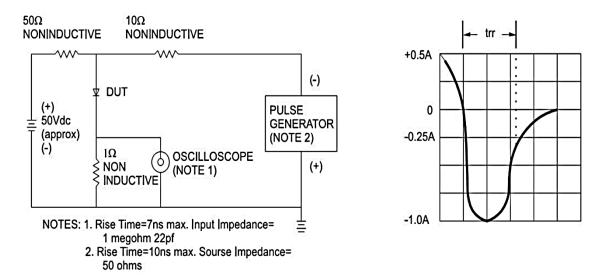
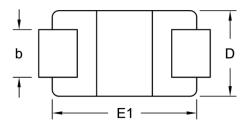


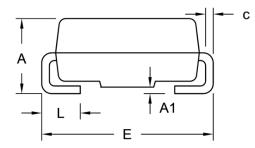
Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

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PACKAGE OUTLINE DIMENSIONS

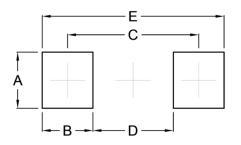
DO-214AC (SMA)





DIM.	Unit (mm)		Unit ((inch)
	Min.	Max.	Min.	Max.
A	1.99	2.50	0.078	0.098
A1	0.10	0.20	0.004	0.008
b	1.27	1.58	0.050	0.062
с	0.15	0.31	0.006	0.012
D	2.29	2.83	0.090	0.111
E	4.95	5.33	0.195	0.210
E1	4.06	4.60	0.160	0.181
L	0.90	1.41	0.035	0.056

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



P/N	= Marking Code
G	= Green Compound
YW	= Date Code

= Factory Code F



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